


 Search ...

PRODUCTS | APPLICATIONS | DESIGN SUPPORT | TRAINING | SAMPLE AND BUY | ABOUT
US | CONTACT US | myMicrochip Login

Product Change Notification - JAON-15VCCB774

Date: 29 Jul 2016
Product Category: Analog (Linear & Mixed Signal) AND Interface
Notification subject: CCB 2593 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI assembly site.
Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:
August 15, 2016 (date code: 1633)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2016					July 2016				August 2016			
Workweek	22	23	24	25	26	27	28	29	30	31	32	33	34
Initial PCN Issue Date			X										
Qual Report Availability									X				
Final PCN Issue Date									X				
Estimated Implementation Date												X	

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
June 13, 2016: Issued initial notification.
July 29, 2016: Issued final notification. Attached the qualification report. Provided estimated first ship date that will be on August 15, 2016

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-15VCCB774_Qual_Report.pdf](#)
 - [PCN_JAON-15VCCB774_Affected_CPN.pdf](#)
 - [PCN_JAON-15VCCB774_Affected_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to **microchipDIRECT** and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."





©Copyright 1998-2016 Microchip Technology Inc. All rights reserved. Shanghai ICP
Recordal No.09049794

JAON-15VCCB774 - CCB 2593 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15VCCB774
CATALOG_PART_NBR
MCP1650R-E/MS
MCP1650RT-E/MS
MCP1650S-E/MS
MCP1650ST-E/MS
MCP1651R-E/MS
MCP1651RT-E/MS
MCP1651S-E/MS
MCP1651ST-E/MS
MCP1652R-E/MS
MCP1652RT-E/MS
MCP1652S-E/MS
MCP1652ST-E/MS
MCP3001-I/MS
MCP3002-I/MS
MCP3201-CI/MS
MCP3201T-CI/MS
MCP3202-CI/MS
MCP3202T-CI/MS
MCP3301-BI/MS
MCP3301-CI/MS
MCP3301T-BI/MS
MCP3301T-CI/MS
MCP6002-E/MS
MCP6002-I/MS
MCP6002T-E/MS
MCP6002T-E/MSHAZ
MCP6002T-I/MS
MCP6021-E/MS
MCP6021T-E/MS
MCP6031-E/MS
MCP6031T-E/MS
MCP6032-E/MS
MCP6032T-E/MS
MCP6033-E/MS
MCP6033T-E/MS
MCP6041-E/MS
MCP6041-I/MS
MCP6041T-E/MS
MCP6041T-I/MS
MCP6042-E/MS
MCP6042-I/MS
MCP6042T-E/MS
MCP6042T-I/MS

JAON-15VCCB774 - CCB 2593 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15VCCB774
CATALOG_PART_NBR
MCP6043-E/MS
MCP6043-I/MS
MCP6043T-E/MS
MCP6043T-I/MS
MCP6141-E/MS
MCP6141-I/MS
MCP6141T-E/MS
MCP6141T-I/MS
MCP6142-E/MS
MCP6142-I/MS
MCP6142T-E/MS
MCP6142T-I/MS
MCP6143-E/MS
MCP6143-I/MS
MCP6143T-E/MS
MCP6143T-I/MS
MCP616-I/MS
MCP616T-I/MS
MCP617-I/MS
MCP617T-I/MS
MCP618-I/MS
MCP618T-I/MS
MCP6231-E/MS
MCP6231T-E/MS
MCP6232-E/MS
MCP6232T-E/MS
MCP6241-E/MS
MCP6241T-E/MS
MCP6242-E/MS
MCP6242T-E/MS
MCP6271-E/MS
MCP6271T-E/MS
MCP6272-E/MS
MCP6272T-E/MS
MCP6273-E/MS
MCP6273T-E/MS
MCP6275-E/MS
MCP6275T-E/MS
MCP6281-E/MS
MCP6281T-E/MS
MCP6282-E/MS
MCP6282T-E/MS
MCP6283-E/MS

JAON-15VCCB774 - CCB 2593 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15VCCB774
CATALOG_PART_NBR
MCP6283T-E/MS
MCP6285-E/MS
MCP6285T-E/MS
MCP6291-E/MS
MCP6291T-E/MS
MCP6292-E/MS
MCP6292-E/MSAAA
MCP6292T-E/MS
MCP6292T-E/MSAAA
MCP6293-E/MS
MCP6293T-E/MS
MCP6295-E/MS
MCP6295T-E/MS
MCP6442-E/MS
MCP6442T-E/MS
MCP6541-E/MS
MCP6541-I/MS
MCP6541T-E/MS
MCP6541T-I/MS
MCP6542-E/MS
MCP6542-I/MS
MCP6542T-E/MS
MCP6542T-I/MS
MCP6543-E/MS
MCP6543-I/MS
MCP6543T-E/MS
MCP6543T-I/MS
MCP6546-E/MS
MCP6546-I/MS
MCP6546T-E/MS
MCP6546T-I/MS
MCP6547-E/MS
MCP6547-I/MS
MCP6547T-E/MS
MCP6547T-I/MS
MCP6548-E/MS
MCP6548-I/MS
MCP6548T-E/MS
MCP6548T-I/MS
MCP6G01-E/MS
MCP6G01T-E/MS
MCP6G02-E/MS
MCP6G02T-E/MS

JAON-15VCCB774 - CCB 2593 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L MSOP package at MTAI site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15VCCB774
CATALOG_PART_NBR
MCP6G03-E/MS
MCP6G03T-E/MS
MCP6L02T-E/MS
MCP6L1T-E/MS
MCP6L2T-E/MS
MCP6L71T-E/MS
MCP6L72T-E/MS
MCP6L91T-E/MS
MCP6L92T-E/MS
MCP6L92T-E/MSHHH
MCP6S21-I/MS
MCP6S21T-I/MS
MCP6S22-I/MS
MCP6S22T-I/MS
MCP6S91-E/MS
MCP6S91T-E/MS
MCP6S92-E/MS
MCP6S92T-E/MS